L Number	Hits	Search Text	DB	Time stamp
2	4609	(257/735-738,777-786).CCLS.	USPAT	2003/01/16 15:46
3	6729	(427/372.2,375,384,385.5,386,407.1).CCLs.	USPAT	1
4	1753	(438/612-618).CCLS.		2003/01/16 15:50
			USPAT	2003/01/16 15:50
5	3129	((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 15:55
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		1
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)		
6	2010	((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 15:56
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
i		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)		
7	210	(((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 15:57
,	210	((427/372.2,375,384,385.5,386,407.1).CCLS.)	USERI	2003/01/10 13.3/
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)) and fatigue		
8	171	((((((257/735-738,777-786).CCLs.)	USPAT	2003/01/16 15:59
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)) and fatigue)		
		and (solidif\$4 solidification densif\$4		
		densification harden\$3 cur\$3)		
9	103	(((((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 16:27
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)) and fatigue)		
		and (solidif\$4 solidification densif\$4		
		densification harden\$3 cur\$3)) and		
		(solvent flux\$4)		
10	914	(((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 16:26
	514	((427/372.2,375,384,385.5,386,407.1).CCLS.)	001111	12003,01,10 10.20
		((438/612-618).CCLS.)) and (reflow\$3		
		re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		
		glu\$3)) and (resin\$3 epoxy)) and (wafer\$1		
		substrate\$1) same (cut\$4 dic\$3 singulat\$3		
11		sever\$3)	HODAM	2002/01/16 16 66
11	851	((((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 16:26
	İ	((427/372.2,375,384,385.5,386,407.1).CCLS.)		1
	ļ	((438/612-618).CCLS.)) and (reflow\$3		
	İ	re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		1
	ļ	pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		1
ļ	İ	glu\$3)) and (resin\$3 epoxy)) and (wafer\$1		
	ļ	substrate\$1) same (cut\$4 dic\$3 singulat\$3		
		sever\$3)) not		
	l	((((((((257/735-738,777-786).CCLS.)		
		((427/372.2,375,384,385.5,386,407.1).CCLS.)		
		((438/612-618).CCLS.)) and (reflow\$3		
	ŀ	re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1		
		pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky		1
		glu\$3)) and (resin\$3 epoxy)) and fatigue)		1
1	1	and (solidif\$4 solidification densif\$4		
		densification harden\$3 cur\$3)) and		
		(solvent flux\$4))		
		1002.000 22007.7/		1

((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))) and (solvent flux\$4) ((((((((((257/735-738,777-786).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (lelectrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((((((257/735-738,777-786).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solvent flux\$4)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solvent flux\$4)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (reflow\$3 re\$lmelt\$3 flow\$3) and (reflow\$3 re\$lmelt\$3 flow\$3) and (reflow\$3 re\$lmelt\$3 flow\$1) and (reflow\$3 re\$lmelt\$3 flow\$1) and (reflow\$3 re\$lmelt\$3 flow\$1) and (reflow\$3 re\$lmelt\$4 flow\$1) and (reflow\$3 re\$lmelt\$4 flow\$1) and (reflow\$3 re\$lmelt\$5 flow\$1) and (reflow\$1 and (solvent flux\$4)) and (reflow\$1 and (solvent flux\$4)) and (reflow\$1 and (solvent flux\$4)) and (solvent flux\$4) and (fill\$3 under\$1fill\$3) 14 20 (((((((((257/735-738,777-786).CCLS.)) (((((((((257/735-738,777-786).CCLS.))) (((((((((257/735-738,777-786).CLS.)))))))					
((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((((((257/735-738,7384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (lectrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4)) (((((((((257/735-738,777-786).CCLS.) ((438/612-618).CCLS.)) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (((((((((((257/735-738,777-786).CCLS.)) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((((((257/735-738,777-786).CCLS.)) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3) ((((((((257/735-738,777-786).CCLS.)) ((427/372.2,375,384,385.5,386,407.1).CCLS.))	12	344	(((((((257/735-738,777-786).CCLS.)	USPAT	2003/01/16 16:29
re\$Imelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solvent flux\$4))) and (solvent flux\$4) densification harden\$3 cur\$3)) and (solvent flux\$4) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) (438/612-618).CCLS.) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3) and (resin\$3 epoxy)) and fatigue) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3) ((((((((2757/35-738,737-786).CCLS.) ((227/372.2,375,384,385.5,386,407.1).CCLS.)			((427/372.2,375,384,385.5,386,407.1).CCLS.)		
pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((((((((257/735-738,777-786).CCLS.) (427/372.2,375,384,385.5,386,407.1).CCLS.) (438/612-618).CCLS.)) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4)) and (fflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not ((((((((257/735-738,777-786).CCLS.) (427/372.2,375,384,385.5,386,407.1).CCLS.) (438/612-618).CCLS.) and (reflow\$3 re\$1melt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (reflow\$3 re\$1melt\$3 flow\$3) and (reflow\$3 re\$1melt\$3 flow\$3) and (reflow\$3 re\$1melt\$3 flow\$3) and (resin\$4 decy\$3 singulat\$3 sever\$3)) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3) and (resin\$3 epoxy)) and fatigue) and (solvent flux\$4))) and (solvent flux\$4)) and (fill\$3 under\$1fill\$3) (USPAT 2003/01/16 17:000000000000000000000000000000000000			((438/612-618).CCLS.)) and (reflow\$3		
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sever\$3)) not ((((((((257/735-738,777-786).CCLS.)) ((427/372.2,375,384,385.5,386,407.1).CCLS.)) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4)) and (solvent flux\$4)) and (solvent flux\$4) ((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and (wafer\$1 substrate\$1) same (cut\$4 dic\$3 singulat\$3 sever\$3)) not (((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) ((448/612-618).CCLS.)) and (reflow\$3 re\$lmelt\$3 flow\$3) and (electrode\$1 bump\$1 pad\$1) and (mount\$3 bond\$3 adhe\$4 tacky glu\$3)) and (resin\$3 epoxy)) and fatigue) and (solidif\$4 solidification densif\$4 densification harden\$3 cur\$3)) and (solvent flux\$4))	!				
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